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[illegible]

Figure 1 is a block diagram of a chip die 130. The diagram illustrates a data path involving several components and long-distance connections. On the left, a multiplexer 132 is connected to an AND gate 152. The output of 152 is connected to an OR gate 154. The output of 154 is connected to a multiplexer 162, which is part of the DEBUG BUS [39:0]. A long-distance connection (40) also links the output of 154 to a multiplexer 160, which is part of the DEBUG BUS [159:140]. Below this, a multiplexer 134 is connected to an AND gate 140. The output of 140 is connected to an OR gate 144. The output of 144 is connected to a multiplexer 135. A long-distance connection (40) also links the output of 140 to a multiplexer 138. In the center, a REGISTER PIPE STAGE 150 is connected to an OR gate 148. The output of 148 is connected to an AND gate 146, which is then connected to multiplexer 138. Another long-distance connection (40) links the output of 148 to the OR gate 144. The chip die 130 is labeled on the right side of the diagram.

FIG. 2

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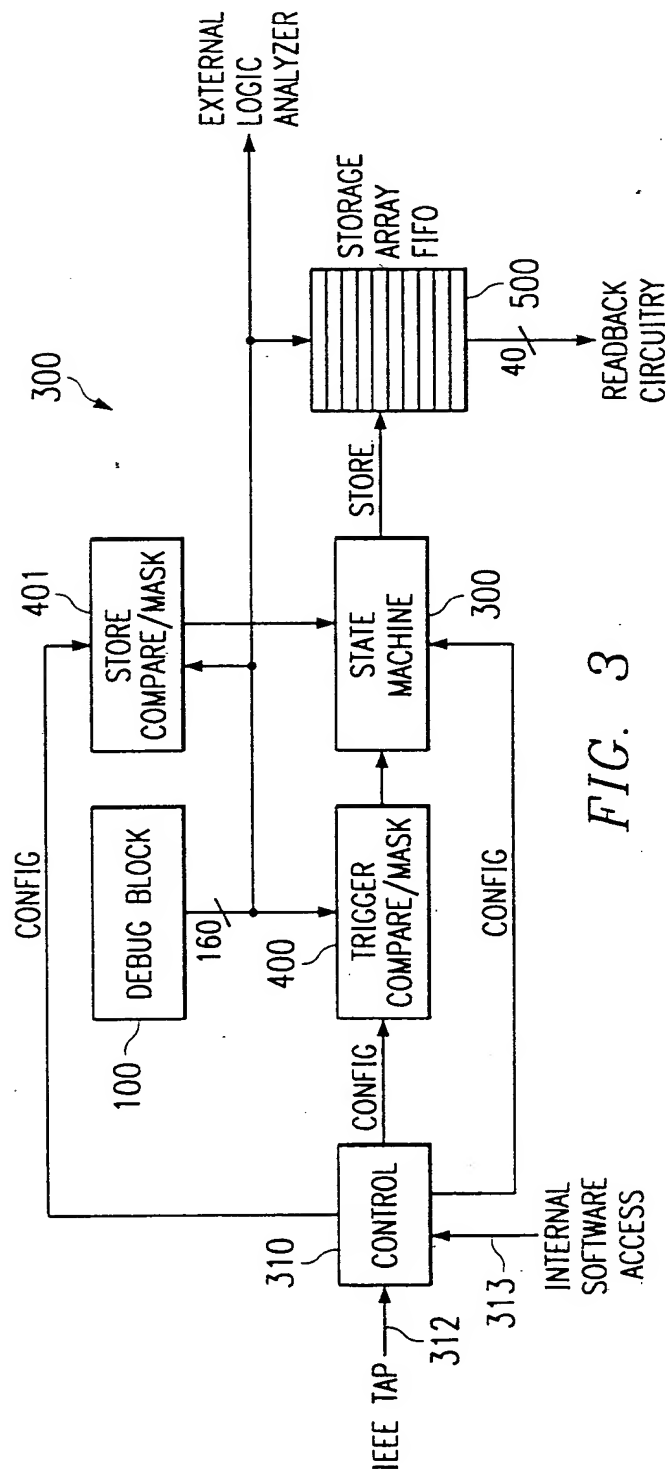
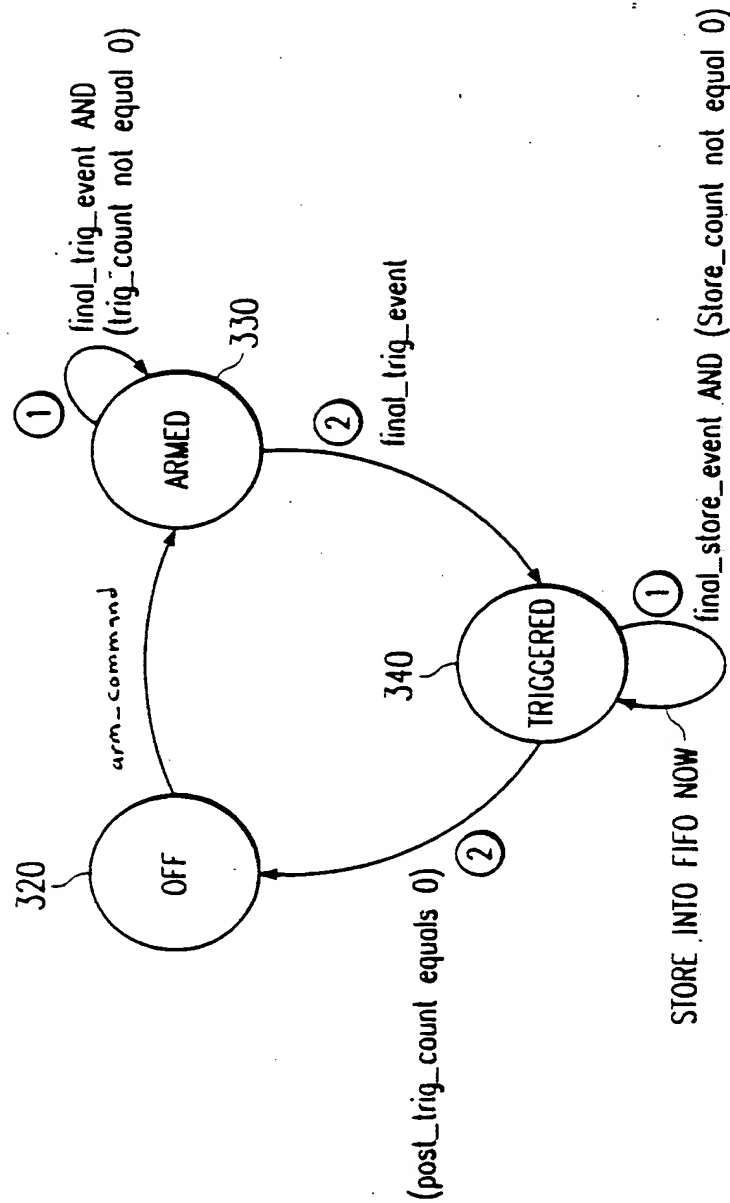


FIG. 3

FIG. 4



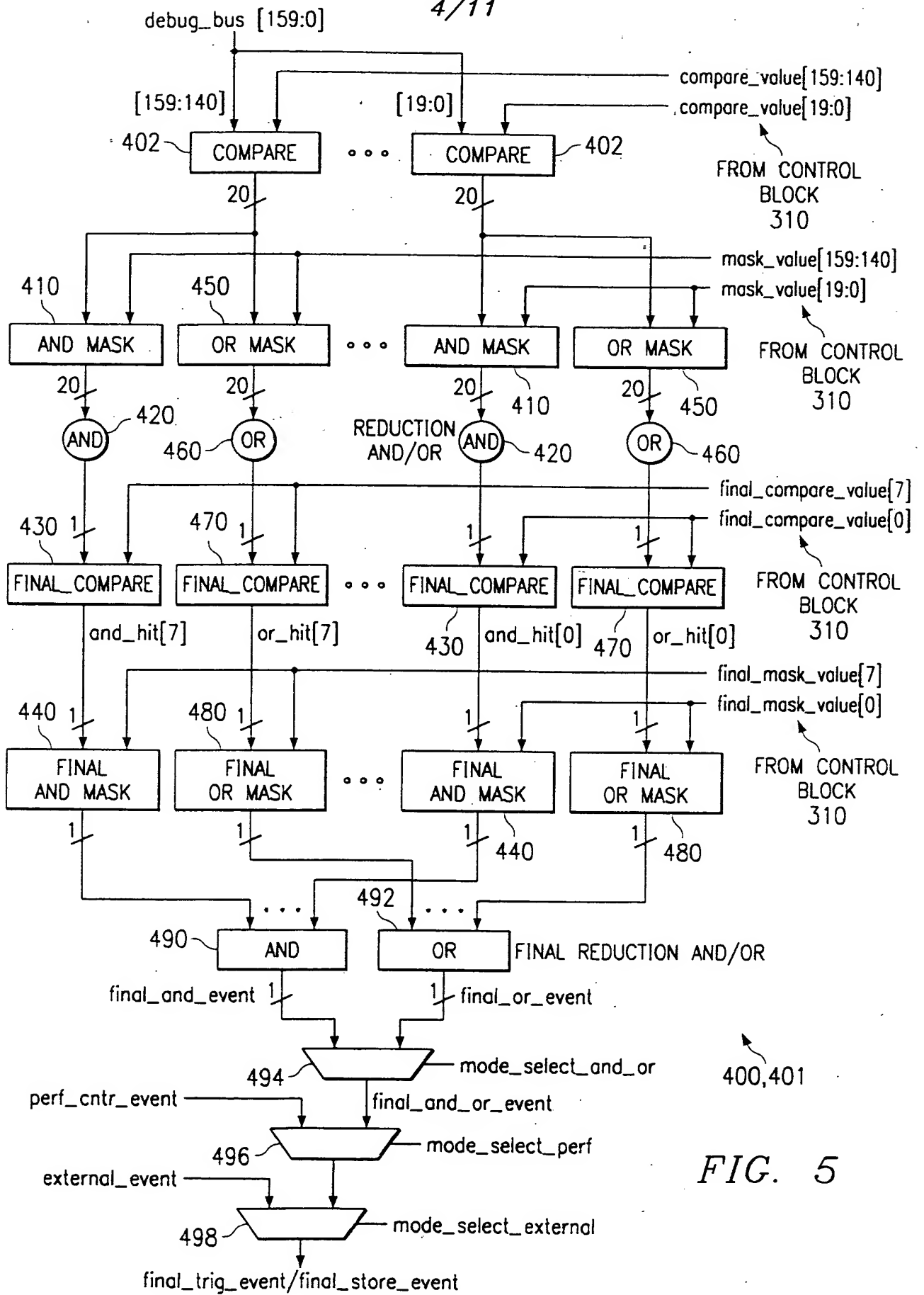
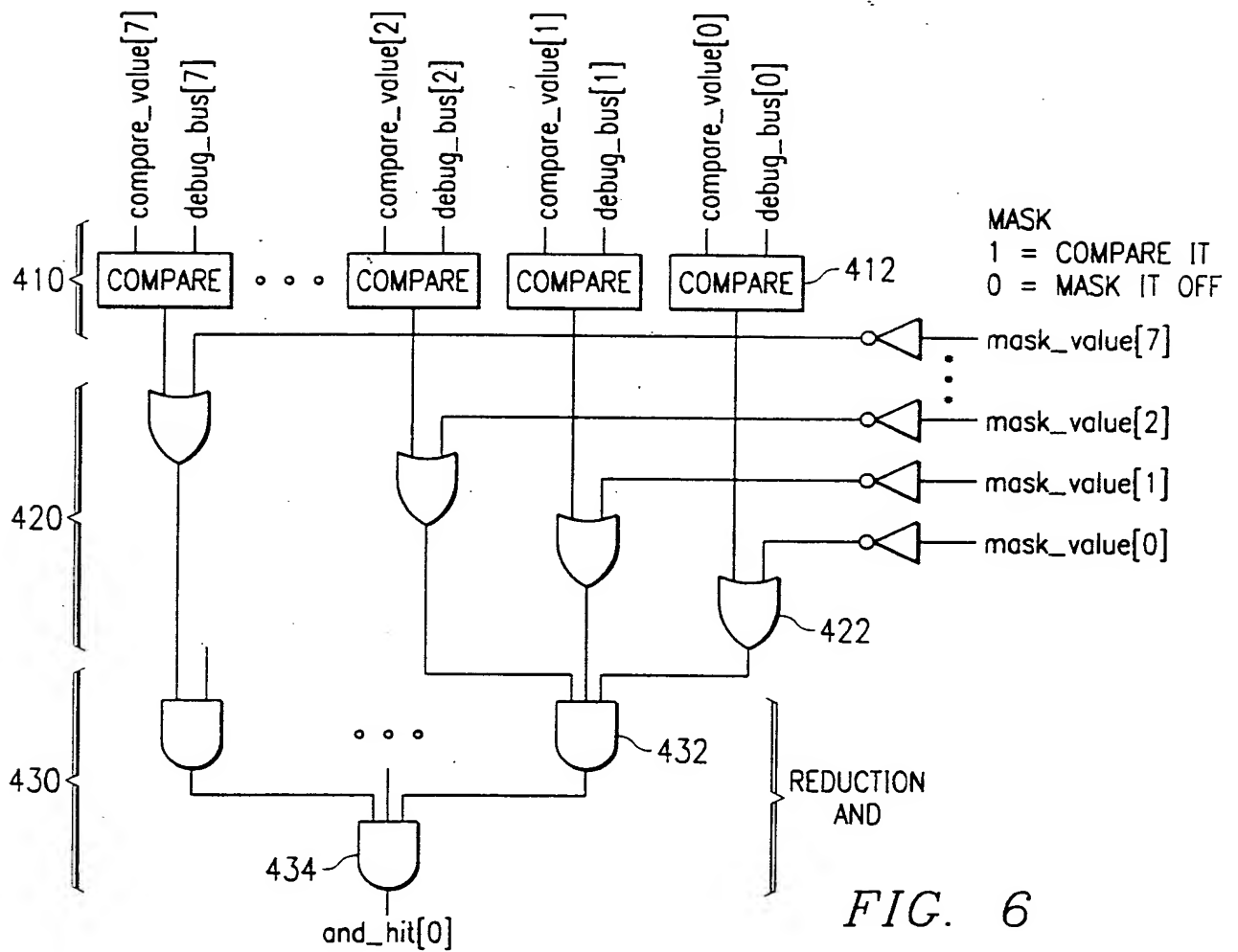
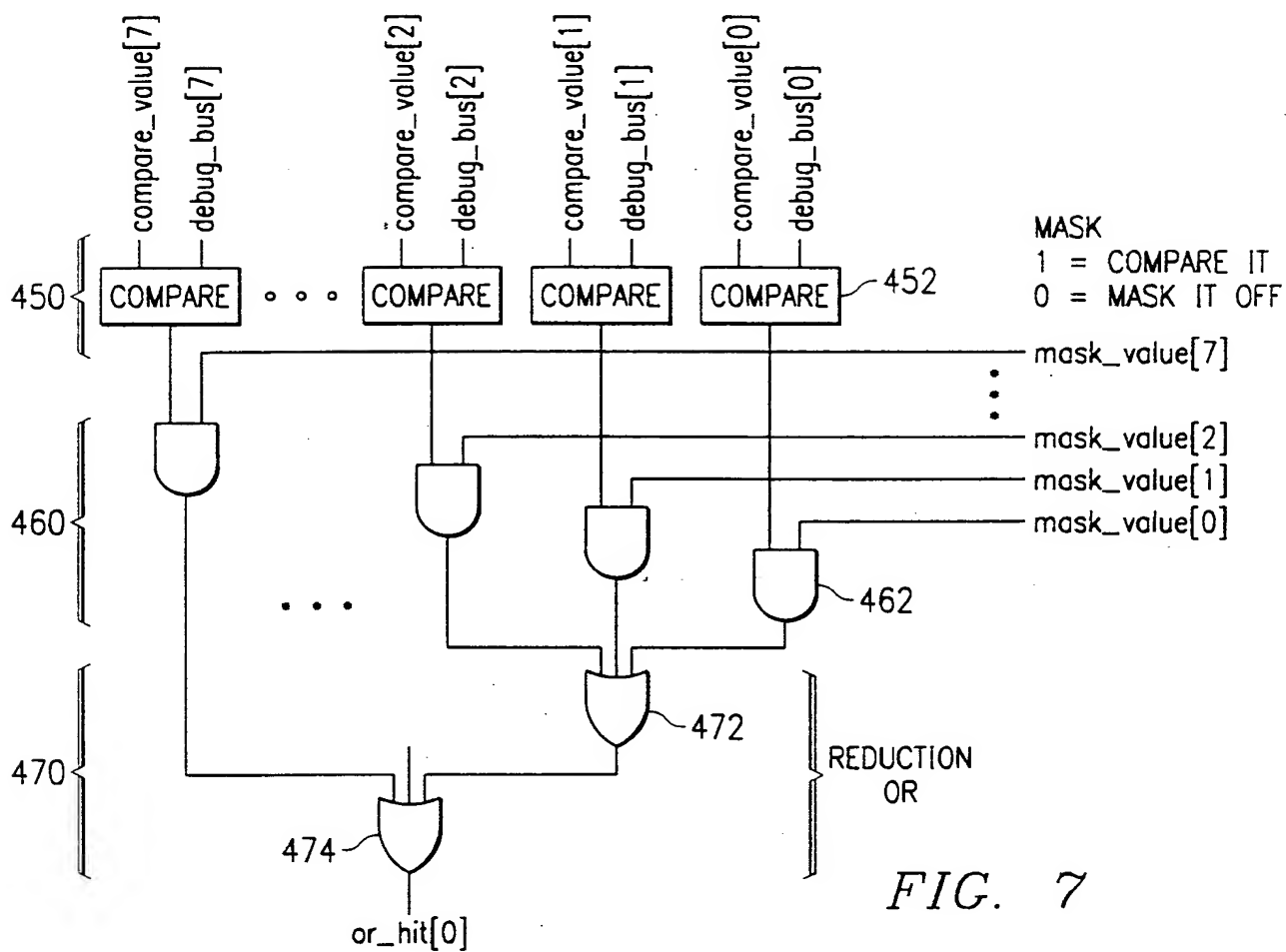


FIG. 5



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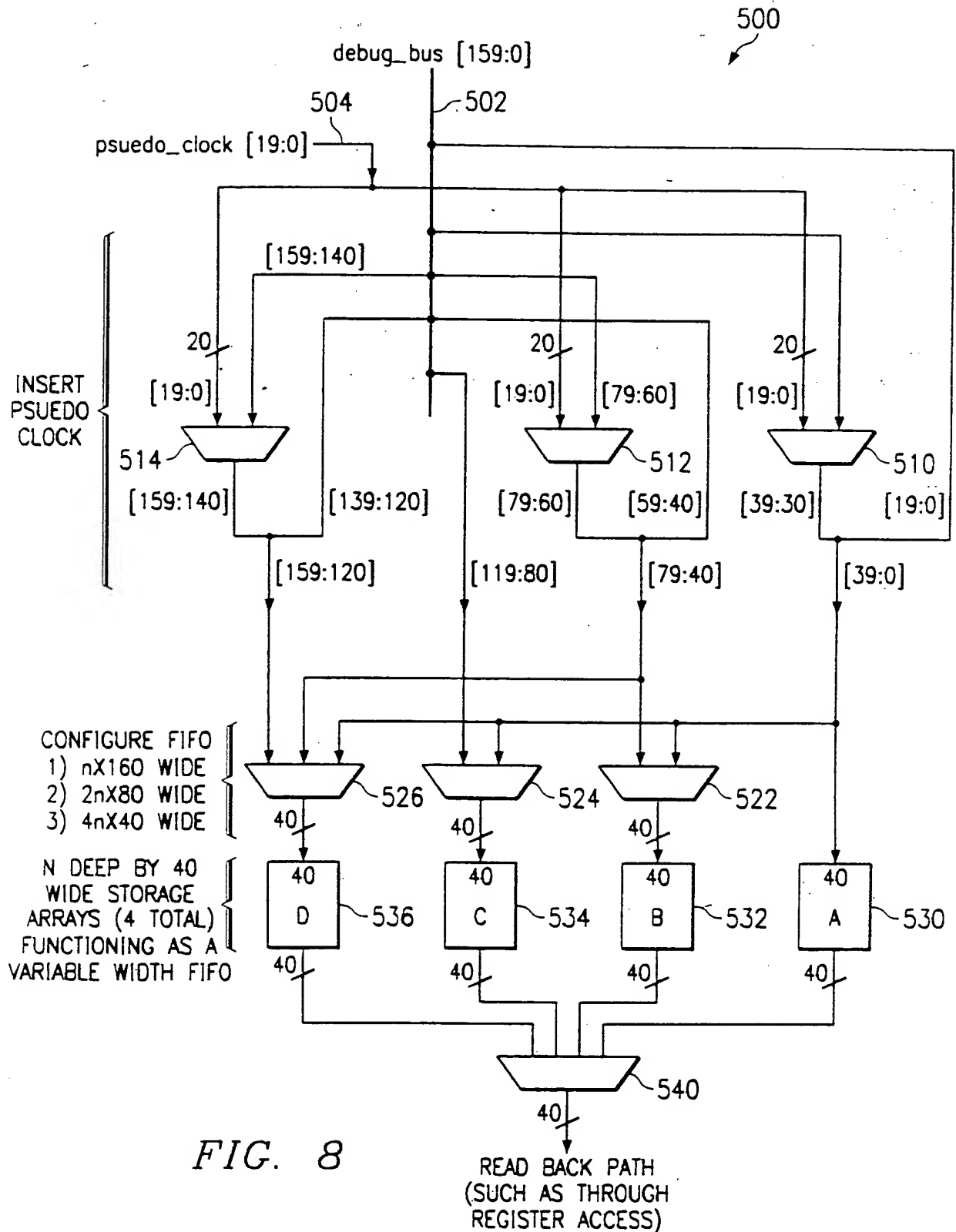


FIG. 8

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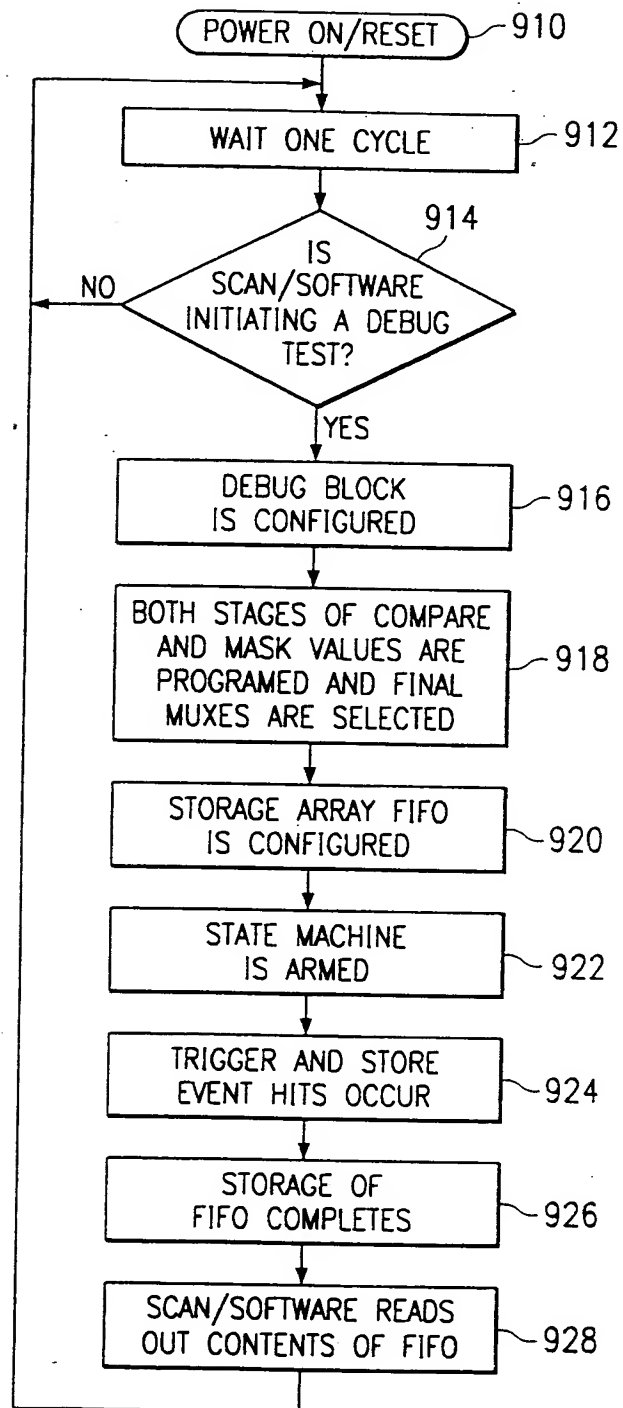


FIG. 9

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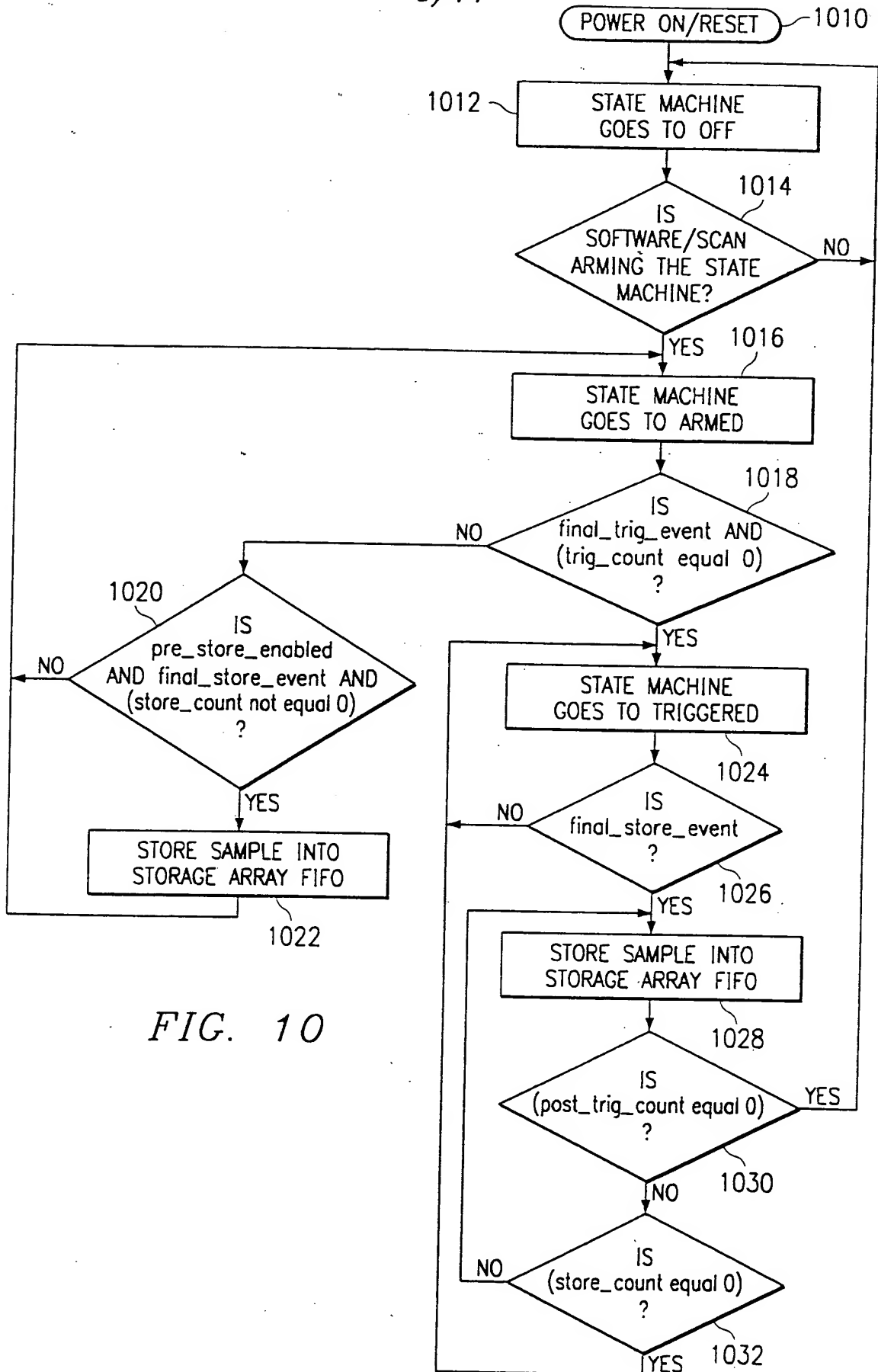


FIG. 10

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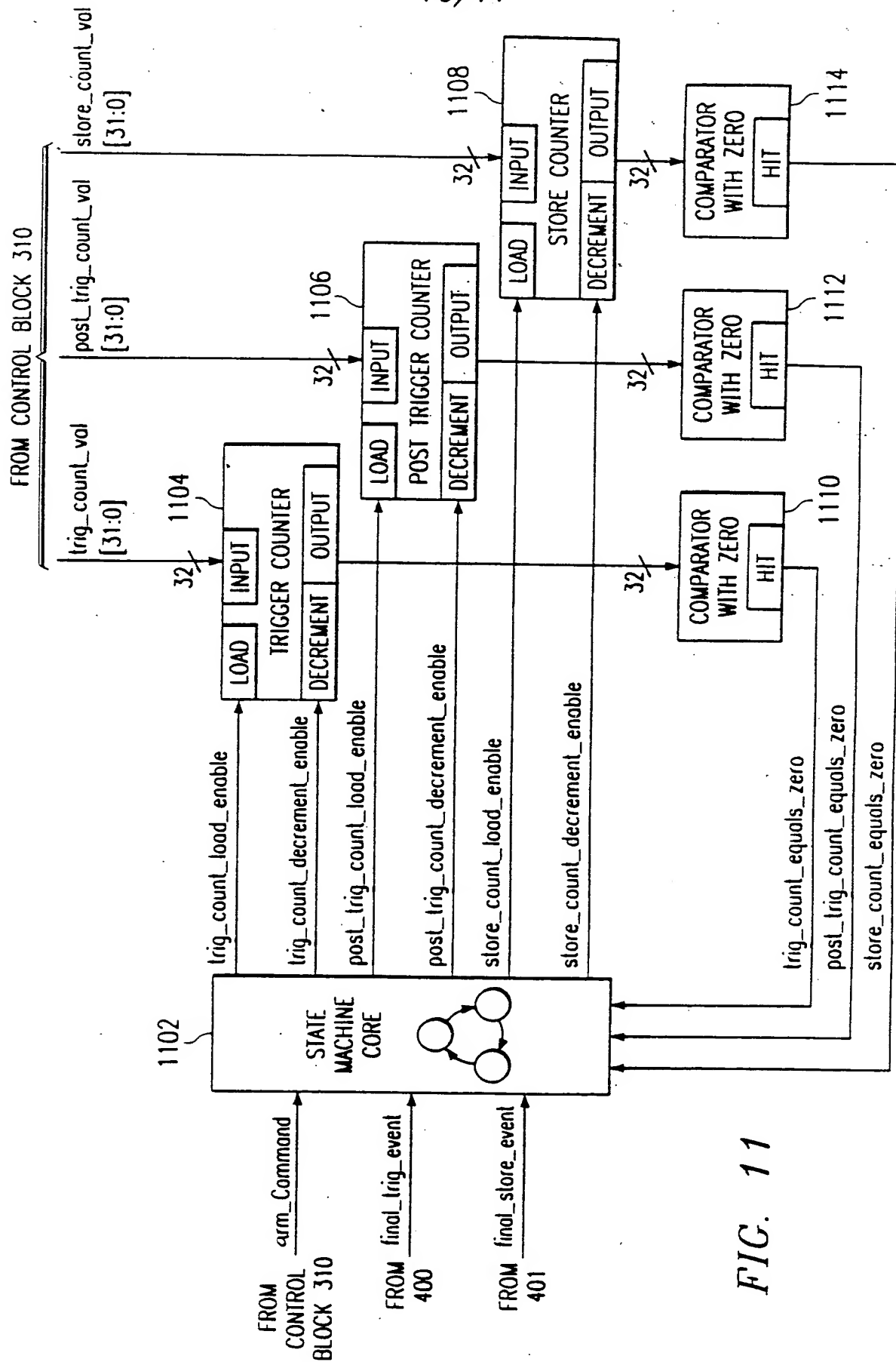


FIG. 11

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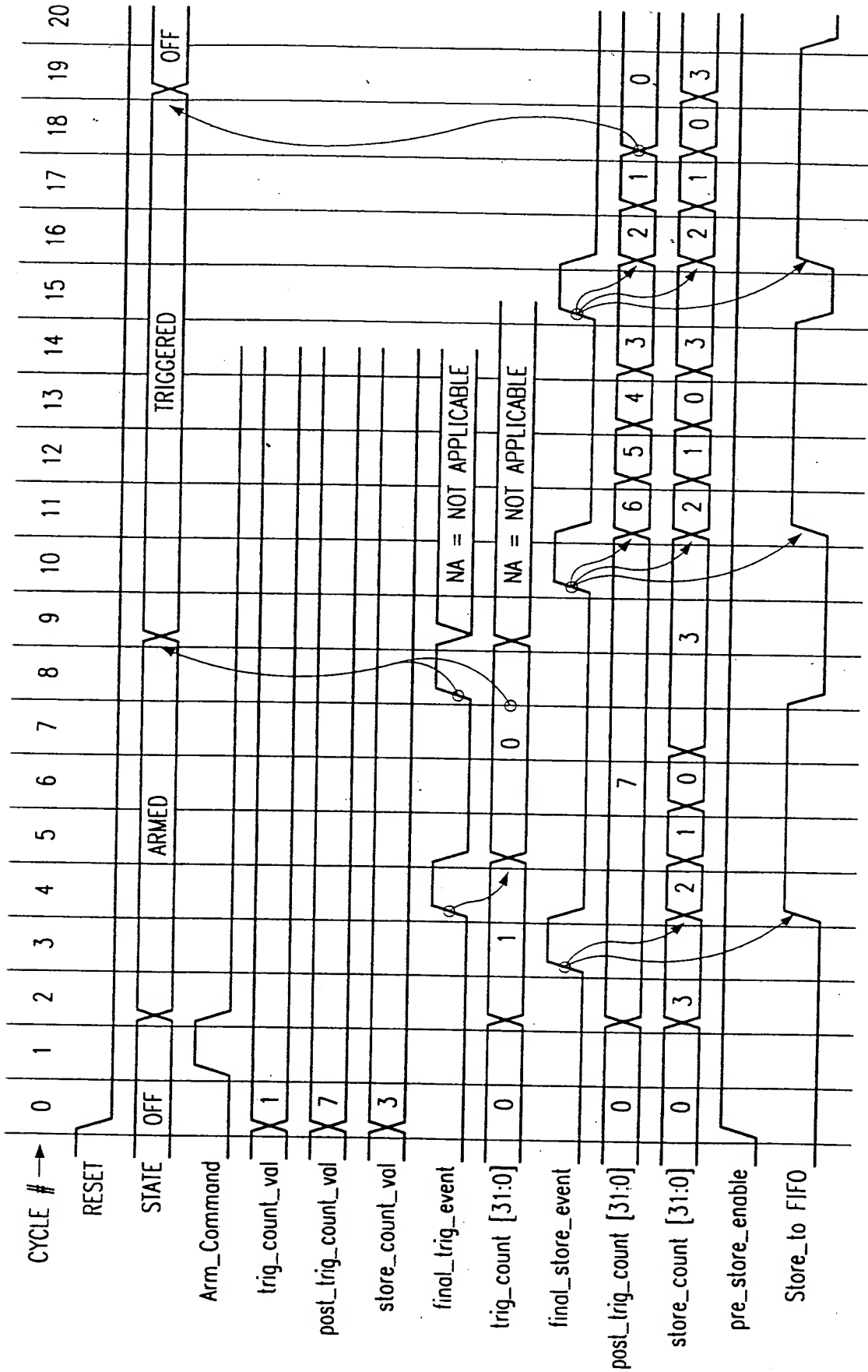


FIG. 12